

# MBR1640FCT THRU MBR16200FCT

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# MBR1640FCT THRU MBR16200FCT

## 16A High Barrier Power Schottky Rectifiers - 40V-200V

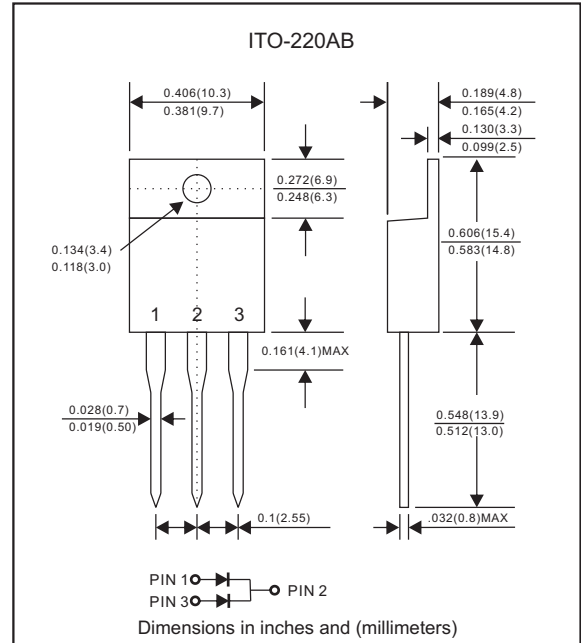
### Features

- 150°C operating junction temperature.
- Low power loss, high efficiency.
- High current capability
- High surge capability.
- Guardring for overvoltage protection.
- Low stored charge majority carrier conduction
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen-free parts, ex. MBR1640FCT-H.

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : JEDEC ITO-220AB molded plastic body over passivated chip
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: As marked
- Mounting Position : Any
- Weight : Approximated 1.70 gram

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	$I_O$			16.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			150	A
Reverse current	$V_R = V_{RRM}$ $T_J = 25^\circ\text{C}$	$I_R$			0.1	mA
	$V_R = V_{RRM}$ $T_J = 125^\circ\text{C}$				20	
Thermal resistance	Junction to case	$R_{\theta JC}$		3.0		$^\circ\text{C}/\text{W}$
Storage temperature range		$T_{STG}$	-65		+175	$^\circ\text{C}$

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	$V_F^{*5}$ (V)	Operating temperature $T_J$ , ( $^\circ\text{C}$ ) -55 to +150
MBR1640FCT	40	28	40	0.70	0.84	
MBR1645FCT	45	31.5	45			
MBR1650FCT	50	35	50	0.80	0.95	
MBR1660FCT	60	42	60			
MBR1680FCT	80	56	80	0.85	0.95	
MBR16100FCT	100	70	100			
MBR16150FCT	150	105	150	0.95	1.00	
MBR16200FCT	200	140	200			

\*1 Repetitive peak reverse voltage

\*2 RMS voltage

\*3 Continuous reverse voltage

\*4 Maximum forward voltage  
 $I_F = 8.0\text{A}$ ,  $25^\circ\text{C}$

\*5 Maximum of forward voltage  
 $I_F = 16.0\text{A}$ ,  $25^\circ\text{C}$

## Rating and characteristic curves (MBR1640FCT THRU MBR16200FCT)

FIG. 1 – FORWARD CURRENT DERATING CURVE

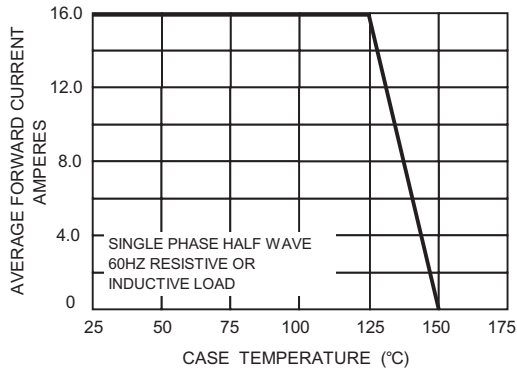


FIG. 2 – MAXIMUM NON-REPETITIVE SURGE CURRENT

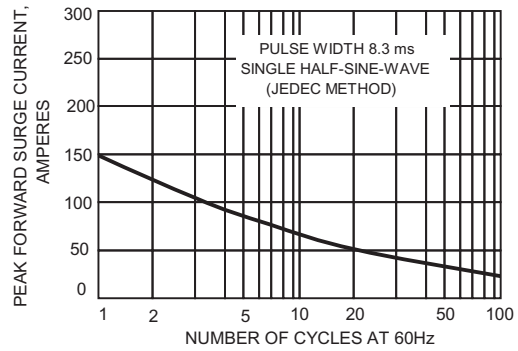


FIG.3-TYPICAL REVER CHARACTERISTICS

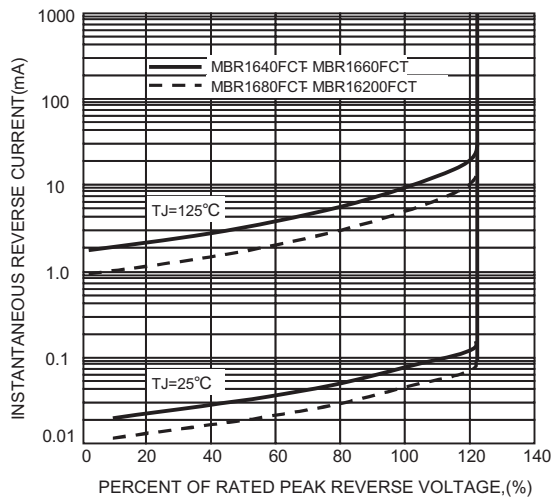


FIG.4-TYPICAL FORWARD CHARACTERISTICS

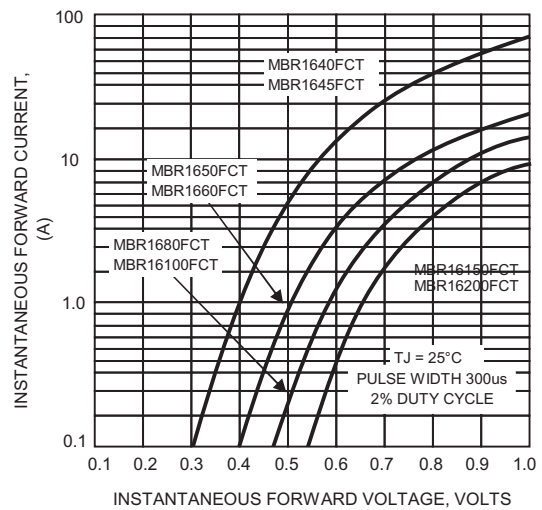
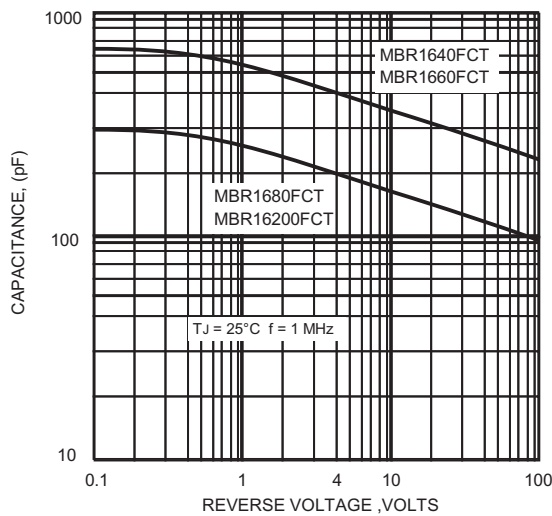
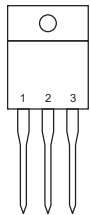
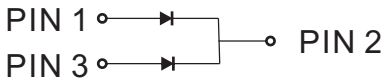


FIG.5 – TYPICAL JUNCTION CAPACITANCE



# MBR1640FCT THRU MBR16200FCT

## Pinning information

Pin	Simplified outline	Symbol
Pin1 anode Pin2 cathode Pin3 anode		

## Marking

Type number	Marking code
MBR1640FCT	MBR1640FCT
MBR1645FCT	MBR1645FCT
MBR1650FCT	MBR1650FCT
MBR1660FCT	MBR1660FCT
MBR1680FCT	MBR1680FCT
MBR16100FCT	MBR16100FCT
MBR16150FCT	MBR16150FCT
MBR16200FCT	MBR16200FCT

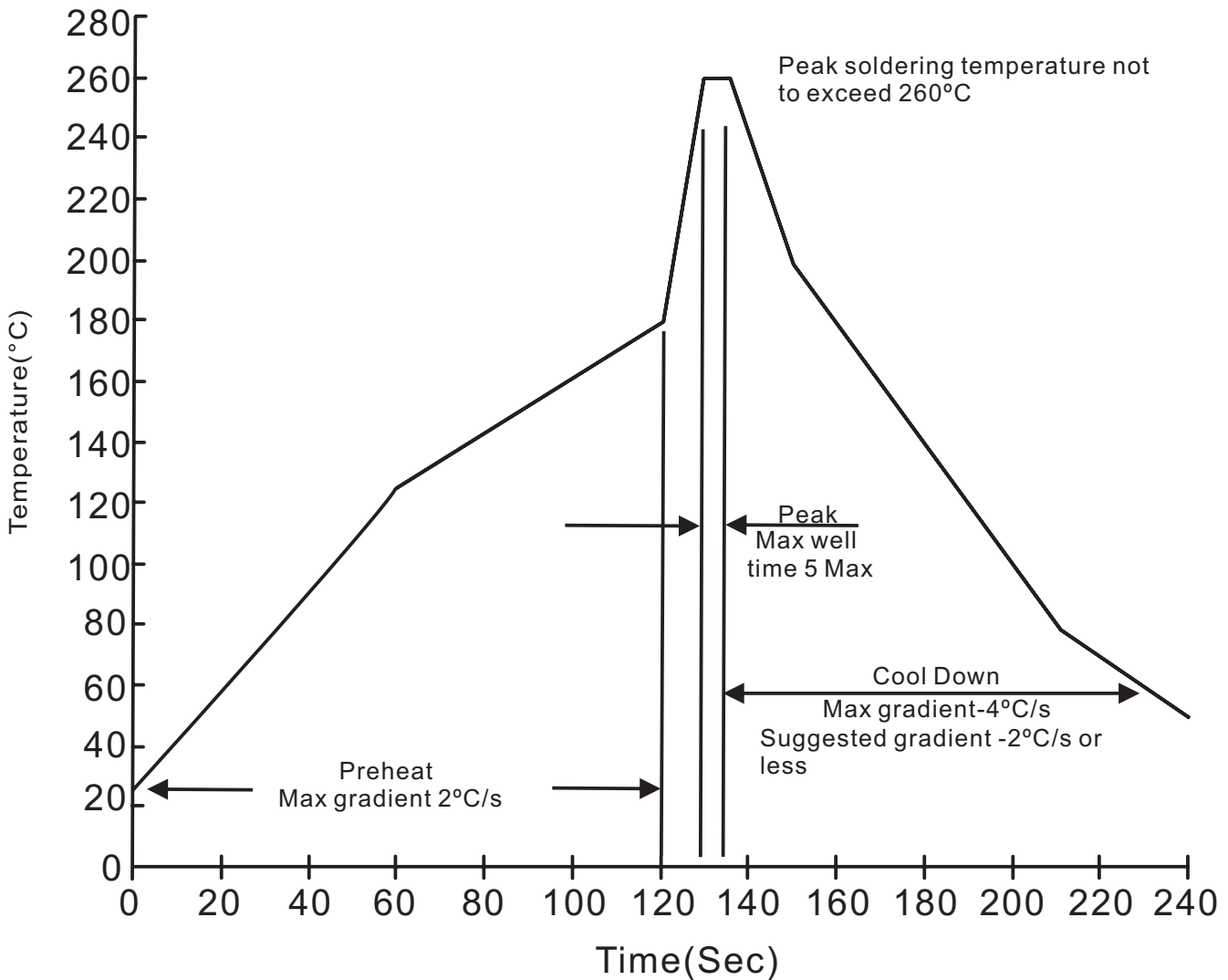
## Tube packing

PACKAGE	TUBE (pcs)	TUBE SIZE (m/m)	BOX (pcs)	INNER BOX (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
ITO-220AB	50	535*32*7.0	2000	550*167*75	570*345*170	8,000	23.0

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## Suggested thermal profiles for soldering processes

### 1. Lead free temperature profile wave-soldering



**MBR1640FCT THRU MBR16200FCT****High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm 5^{\circ}\text{C}$ for $10\pm 2\text{sec}$ . immerse body into solder $1/16''\pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$ , $I_F = I_o$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	$-55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^{\circ}\text{C}$ , RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at $175^{\circ}\text{C}$ for 1000 hrs.	MIL-STD-750D METHOD-1031